



## Product Change Notification / JAON-28ACMH770

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### Date:

30-Jun-2020

### Product Category:

16-Bit - Microcontrollers and Digital Signal Controllers, 32-bit Microcontrollers, Capacitive Touch Sensors, Ethernet Controllers, Sensor Fusion Hub

### PCN Type:

Manufacturing Change

### Notification Subject:

CCB 4156.001 and 4156.002 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 44L QFN (8x8x0.9mm), 28L QFN-S (6x6x0.9mm) and 28L QFN (6x6x0.9mm) packages at MTAI assembly site.

### Affected CPNs:

[JAON-28ACMH770\\_Affected\\_CPN\\_06302020.pdf](#)

[JAON-28ACMH770\\_Affected\\_CPN\\_06302020.csv](#)

### Notification Text:

**PCN Status:** Final notification

**PCN Type:** Manufacturing Change

**Microchip Parts Affected:** Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

**Description of Change:** Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 44L QFN (8x8x0.9mm), 28L QFN-S (6x6x0.9mm) and 28L QFN (6x6x0.9mm) packages at MTAI assembly site.

#### Pre Change:

Using gold (Au) bond wire

#### Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire

**Pre and Post Change Summary:**

	<b>Pre Change</b>	<b>Post Change</b>
<b>Assembly Site</b>	Microchip Technology Thailand HQ (MTAI)	Microchip Technology Thailand HQ (MTAI)
<b>Lead frame material</b>	C194	C194
<b>Bond wire material</b>	Au wire	CuPdAu wire
<b>Die attach material</b>	3280	3280
<b>Mold compound material</b>	G700LTD	G700LTD

**Impacts to Data Sheet:** None

**Change Impact:**None

**Reason for Change:**To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire at MTAI assembly site.

**Change Implementation Status:**In Progress

**Estimated First Ship Date:**July 24, 2020 (date code: 2030)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Time Table Summary:**

	<b>June 2020</b>					<b>July 2020</b>			
Workweek	23	24	25	26	27	28	29	30	31
Qual Report Availability					X				
Final PCN Issue Date					X				
Estimated Implementation Date								X	

**Method to Identify Change:** Traceability code

**Qualification Report:**Please open the attachments included with this PCN labeled as PCN\_#\_Qual Report.

**Revision History: June 30, 2020:** Issued final notification. Attached the qualification report. Provided estimated first ship date to be on July 24, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

## **Attachments:**

[PCN\\_JAON-28ACMH770\\_Qual\\_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

## **Terms and Conditions:**

If you wish to receive Microchip PCNs via email please register for our PCN email service at our [PCN home page](#) select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the [PCN FAQ](#) section.

If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.



## **QUALIFICATION REPORT SUMMARY**

### **RELIABILITY LABORATORY**

**PCN #: JAON-28ACMH770**

**Date**  
**June 11, 2020**

**Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 64L QFN (9x9x0.9mm) package at MTAI assembly site. The qualification of CuPdAu bond wire for selected products available in 44L QFN (8x8x0.9mm), 28L QFN-S (6x6x0.9mm) and 28L QFN (6x6x0.9mm) packages will qualify by similarity (QBS).**



## MICROCHIP PACKAGE QUALIFICATION REPORT

**Purpose** Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 64L QFN (9x9x0.9mm) package at MTAI assembly site. The qualification of CuPdAu bond wire for selected products available in 44L QFN (8x8x0.9mm), 28L QFN-S (6x6x0.9mm) and 28L QFN (6x6x0.9mm) packages will qualify by similarity (QBS).

**CN** ES338496

**QUAL ID** R2000128 rev A

**MP CODE** TLAk17R4XQDB

**Part No.** DSPIC33EP256GM306-I/MR

**Bonding No.** BDM-002348 Rev. A

**CCB No.** 4156, 4156.001 and 4156.002

### Package

**Type** 64L QFN

**Package size** 9x9x0.9 mm

### Lead Frame

**Paddle size** 264 x 264 mils

**Material** C194

**Surface** Bare Cu DAP

**Process** Etched

**Lead Lock** Yes

**Part Number** 10106409

### Material

**Epoxy** 3280

**Wire** CuPdAu wire

**Mold Compound** G700LTD

**Plating Composition** Matte Tin



## MICROCHIP PACKAGE QUALIFICATION REPORT

### Manufacturing Information

Assembly Lot No.	Wafer Lot No.
MTAI204702400.000	TC11920432228.110
MTAI204702401.000	TC11920432228.120
MTAI204702849.000	TC11920432228.110

### Result

Pass  Fail  \_\_\_\_\_

64L QFN (9x9x0.9 mm) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

# PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
<b><u>Precondition Prior Perform Reliability Tests (At MSL Level 1)</u></b>	<b>Electrical Test:</b> +25°C and 85°C System: J750  Bake 150°C, 24 hrs System: CHINEE  85°C/85%RH Moisture Soak 168 hrs.  System: TABAI ESPEC Model PR-3SPH  3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243  <b>Electrical Test:</b> +25°C and 85°C System: J750	JESD22- A113  JIP/ IPC/JEDE C J-STD- 020E	693(0)	693  693  693  693  0/693	Pass	Good Devices

# PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>Temp Cycle</b>	<b>Stress Condition:</b> -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H <b>Electrical Test:</b> + 85°C System: J750	JESD22-A104		231		Parts had been pre-conditioned at 260°C 77 units / lot
	<b>Stress Condition:</b> -65°C to +150°C, 1000 Cycles System: TABAI ESPEC TSA-70H <b>Electrical Test:</b> +85°C System: J750		231(0)	0/231	Pass	
	<b>Bond Strength:</b> Wire Pull (> 2.5 grams) Bond Shear (>15.00 grams)		15 (0)	0/15	Pass	
			15 (0)	0/15	Pass	
<b>UNBIASED-HAST</b>	<b>Stress Condition:</b> +130°C/85%RH, 96 hrs. System: HAST 6000X <b>Electrical Test:</b> +25°C System: J750	JESD22-A118		231		Parts had been pre-conditioned at 260°C 77 units / lot
	<b>Stress Condition:</b> +130°C/85%RH, 192 hrs. System: HAST 6000X <b>Electrical Test:</b> + 25°C System: J750		231(0)	0/231	Pass	
			231(0)	0/231	Pass	
<b>HAST</b>	<b>Stress Condition:</b> +130°C/85%RH, 96 hrs. <b>Bias Volt:</b> 3.6Volts, 1.98 Volts System: HAST 6000X <b>Electrical Test:</b> + 25°C and 85°C System: J750	JESD22-A110		231		Parts had been pre-conditioned at 260°C 77 units / lot
	<b>Stress Condition:</b> +130°C/85%RH, 192 hrs. <b>Bias Volt:</b> 3.6Volts, 1.98 Volts System: HAST 6000X <b>Electrical Test:</b> + 25°C and 85°C System: J750		231(0)	0/231	Pass	
			231(0)	0/231	Pass	



# PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
<b>High Temperature Storage Life</b>	<b>Stress Condition:</b> Bake 175°C, 500 hrs System: SHEL LAB	JESD22- A103		45		45 units
	<b>Electrical Test:</b> +25°C and 85°C System: J750		45(0)	0/45	Pass	
	<b>Stress Condition:</b> Bake 175°C, 1000 hrs System: SHEL LAB			45		
	<b>Electrical Test:</b> +25°C and 85°C System: J750		45 (0)	0/45	Pass	
<b>Physical Dimensions</b>	Physical Dimension, 10 units from 1 lot	JESD22- B100/B108	30(0) Units	0/30	Pass	
<b>Bond Strength</b>	Wire Pull (> 2.5 grams)	M2011	30 (0) Wires	0/30	Pass	
<b>Data Assembly</b>	Bond Shear (>15.00 grams)	JESD22- B116	30 (0) bonds	0/30	Pass	

Affected Catalog Part Numbers (CPN)

ENC424J600-I/ML  
ENC424J600T-I/ML  
DSPIC33EP512GP504-E/ML  
DSPIC33EP512MC204-E/ML  
DSPIC33EP512MC504-E/ML  
PIC24EP512GP204-E/ML  
PIC24EP512MC204-E/ML  
DSPIC33EP512GP504-I/ML  
DSPIC33EP512MC204-I/ML  
DSPIC33EP512MC504-I/ML  
PIC24EP512GP204-I/ML  
PIC24EP512MC204-I/ML  
DSPIC33EP512GP504T-H/ML  
DSPIC33EP512MC204T-H/ML  
DSPIC33EP512MC504T-H/ML  
PIC24EP512GP204T-H/ML  
PIC24EP512MC204T-H/ML  
DSPIC33EP512GP504-H/ML  
DSPIC33EP512MC204-H/ML  
DSPIC33EP512MC504-H/ML  
PIC24EP512GP204-H/ML  
PIC24EP512MC204-H/ML  
DSPIC33EP512GP504T-I/ML  
DSPIC33EP512MC204T-I/ML  
DSPIC33EP512MC504T-I/ML  
PIC24EP512GP204T-I/ML  
PIC24EP512MC204T-I/ML  
DSPIC33EP512MC204T-E/ML  
DSPIC33EP512MC504T-E/ML  
PIC24EP512GP204T-E/ML  
PIC24EP512MC204T-E/ML  
DSPIC33EP64GP504-E/ML  
DSPIC33EP64MC204-E/ML  
DSPIC33EP64MC504-E/ML  
PIC24EP64GP204-E/ML  
PIC24EP64MC204-E/ML  
DSPIC33EP64GP504-I/MLA3  
DSPIC33EP64GP504-I/ML  
DSPIC33EP64MC204-I/ML  
DSPIC33EP64MC504-I/ML  
PIC24EP64GP204-I/ML  
PIC24EP64MC204-I/ML  
DSPIC33EP64GP504T-H/ML  
DSPIC33EP64MC204T-H/ML  
DSPIC33EP64MC504T-H/ML  
PIC24EP64GP204T-H/ML

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JAON-28ACMH770 - CCB 4156.001 and 4156.002 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) bond wire for selected products available in 44L QFN (8x8x0.9mm), 28L QFN-S (6x6x0.9mm) and 28L QFN (6x6x0.9mm) packages at MTAI assembly site.

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PIC24EP64MC204T-H/ML

DSPIC33EP64GP504-H/ML

DSPIC33EP64MC204-H/ML

DSPIC33EP64MC504-H/ML

PIC24EP64GP204-H/ML

PIC24EP64MC204-H/ML

DSPIC33EP64GP504T-I/ML

DSPIC33EP64MC204T-I/ML

DSPIC33EP64MC504T-I/ML

PIC24EP64GP204T-I/ML

PIC24EP64MC204T-I/ML

DSPIC33EP64GP504T-E/ML

DSPIC33EP64MC204T-E/ML

DSPIC33EP64MC504T-E/ML

PIC24EP64GP204T-E/ML

PIC24EP64MC204T-E/ML

DSPIC33EP128GP504-E/ML

DSPIC33EP128MC204-E/ML

DSPIC33EP128MC504-E/ML

PIC24EP128GP204-E/ML

PIC24EP128MC204-E/ML

DSPIC33EP128GP504-I/ML

DSPIC33EP128MC204-I/ML

DSPIC33EP128MC504-I/ML

PIC24EP128GP204-I/ML

PIC24EP128MC204-I/ML

DSPIC33EP128MC504T-H/ML

DSPIC33EP128GP504-H/ML

DSPIC33EP128MC204-H/ML

DSPIC33EP128MC504-H/ML

PIC24EP128GP204-H/ML

PIC24EP128MC204-H/ML

DSPIC33EP128GP504T-I/ML

DSPIC33EP128MC204T-I/ML

DSPIC33EP128MC504T-I/ML

PIC24EP128GP204T-I/ML

PIC24EP128MC204T-I/ML

DSPIC33EP128GP504T-E/ML

DSPIC33EP128MC204T-E/ML

DSPIC33EP128MC504T-E/ML

DSPIC33EP256GP504-E/ML

DSPIC33EP256MC204-E/ML

DSPIC33EP256MC504-E/ML

PIC24EP256GP204-E/ML

PIC24EP256MC204-E/ML

HA7619-I/ML027

DSPIC33EP256GP504-I/ML

DSPIC33EP256MC204-I/ML

DSPIC33EP256MC504-I/ML

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PIC24EP256GP204-I/ML

PIC24EP256MC204-I/ML

DSPIC33EP256GP504T-H/ML

DSPIC33EP256MC204T-H/ML

DSPIC33EP256MC504T-H/ML

PIC24EP256GP204T-H/ML

PIC24EP256MC204T-H/ML

DSPIC33EP256GP504-H/ML

DSPIC33EP256MC204-H/ML

DSPIC33EP256MC504-H/ML

PIC24EP256GP204-H/ML

PIC24EP256MC204-H/ML

HA7619T-I/ML025

HA7619T-I/ML027

PIC24EP256GP204T-I/ML029

DSPIC33EP256GP504T-I/ML

DSPIC33EP256MC204T-I/ML

DSPIC33EP256MC504T-I/ML

PIC24EP256GP204T-I/ML

PIC24EP256MC204T-I/ML

DSPIC33EP256MC204T-E/MLC02

DSPIC33EP256GP504T-E/ML

DSPIC33EP256MC204T-E/ML

DSPIC33EP256MC504T-E/ML

PIC24EP256GP204T-E/ML

PIC24EP256MC204T-E/ML

DSPIC33EP32GP504-E/ML

DSPIC33EP32MC204-E/ML

DSPIC33EP32MC504-E/ML

PIC24EP32GP204-E/ML

PIC24EP32MC204-E/ML

DSPIC33EP32GP504-I/ML

DSPIC33EP32MC204-I/ML

DSPIC33EP32MC504-I/ML

PIC24EP32GP204-I/ML

PIC24EP32MC204-I/ML

DSPIC33EP32GP504T-H/ML

DSPIC33EP32MC204T-H/ML

DSPIC33EP32MC504T-H/ML

PIC24EP32GP204T-H/ML

PIC24EP32MC204T-H/ML

DSPIC33EP32GP504-H/ML

DSPIC33EP32MC204-H/ML

DSPIC33EP32MC504-H/ML

PIC24EP32GP204-H/ML

PIC24EP32MC204-H/ML

DSPIC33EP32GP504T-I/ML

DSPIC33EP32MC204T-I/ML

DSPIC33EP32MC504T-I/ML

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Date: Tuesday, June 30, 2020

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PIC24EP32GP204T-I/ML  
PIC24EP32MC204T-I/ML  
DSPIC33EP32GP504T-E/ML  
DSPIC33EP32MC204T-E/ML  
DSPIC33EP32MC504T-E/ML  
PIC24EP32GP204T-E/ML  
PIC24EP32MC204T-E/ML  
WP200TX01-E/ML001  
DSPIC33EP64GS504-E/MLC06  
DSPIC33EP64GS504-E/ML  
DSPIC33EP32GS504-E/ML  
DSPIC33EP16GS504-E/ML  
DSPIC33EP32GS504-I/MLC09  
DSPIC33EP32GS504-I/MLC10  
DSPIC33EP64GS504-I/MLC11  
DSPIC33EP64GS504-I/ML  
DSPIC33EP32GS504-I/ML  
DSPIC33EP16GS504-I/ML  
DSPIC33EP32GS504T-I/MLC09  
DSPIC33EP32GS504T-I/MLC10  
DSPIC33EP64GS504T-I/MLC11  
DSPIC33EP64GS504T-I/ML  
DSPIC33EP32GS504T-I/ML  
DSPIC33EP16GS504T-I/ML  
WP200TX01T-E/ML001  
DSPIC33EP64GS504T-E/ML  
DSPIC33EP32GS504T-E/ML  
DSPIC33EP16GS504T-E/ML  
DSPIC33EP128GM304-E/ML  
DSPIC33EP128GM604-E/ML  
DSPIC33EP256GM304-E/ML  
DSPIC33EP256GM604-E/ML  
DSPIC33EP512GM304-E/ML  
DSPIC33EP512GM604-E/ML  
DSPIC33EP128GM304-I/ML  
DSPIC33EP128GM604-I/ML  
DSPIC33EP256GM304-I/ML  
DSPIC33EP256GM604-I/ML  
DSPIC33EP512GM304-I/ML  
DSPIC33EP512GM604-I/ML  
DSPIC33EV128GM004-E/ML  
DSPIC33EV128GM104-E/ML  
DSPIC33EV64GM004-E/ML  
DSPIC33EV64GM104-E/ML  
DSPIC33EV32GM004-E/ML  
DSPIC33EV32GM104-E/ML  
DSPIC33EV128GM004-I/ML  
DSPIC33EV128GM104-I/ML  
DSPIC33EV64GM004-I/ML

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DSPIC33EV64GM104-I/ML  
DSPIC33EV32GM004-I/ML  
DSPIC33EV32GM104-I/ML  
DSPIC33EV128GM004-H/ML  
DSPIC33EV128GM104-H/ML  
DSPIC33EV64GM004-H/ML  
DSPIC33EV64GM104-H/ML  
DSPIC33EV32GM004-H/ML  
DSPIC33EV32GM104-H/ML  
DSPIC33EV128GM004T-I/ML  
DSPIC33EV128GM104T-I/ML  
DSPIC33EV64GM004T-I/ML  
DSPIC33EV64GM104T-I/ML  
DSPIC33EV32GM004T-I/ML  
DSPIC33EV32GM104T-I/ML  
DSPIC33EV256GM004-E/ML  
DSPIC33EV256GM104-E/ML  
DSPIC33EV256GM004-I/ML  
DSPIC33EV256GM104-I/ML  
DSPIC33EV256GM004-H/ML  
DSPIC33EV256GM104-H/ML  
DSPIC33EV256GM004T-I/ML  
DSPIC33EV256GM104T-I/ML  
PIC24FJ128GB204-E/ML  
PIC24FJ64GB204-E/ML  
PIC24FJ128GB204-I/ML  
PIC24FJ64GB204-I/ML  
PIC24FJ128GB204T-I/ML  
PIC24FJ64GA204-E/ML  
PIC24FJ128GA204-I/ML  
PIC24FJ64GA204-I/ML  
PIC24FJ128GA204T-I/ML  
PIC24FJ64GA204T-I/ML  
PIC32MX174F256D-I/ML  
PIC32MX274F256D-I/ML  
PIC32MX154F128D-I/ML  
PIC32MX254F128D-I/ML  
PIC32MX174F256D-V/ML  
PIC32MX274F256D-V/ML  
PIC32MX154F128D-V/ML  
PIC32MX254F128D-V/ML  
PIC32MX174F256DT-V/ML  
PIC32MX274F256DT-V/ML  
PIC32MX154F128DT-V/ML  
PIC32MX254F128DT-V/ML  
PIC32MX174F256DT-I/ML  
PIC32MX274F256DT-I/ML  
PIC32MX154F128DT-I/ML  
PIC32MX254F128DT-I/ML

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MTCH6301-I/ML

PIC32MX120F032D-I/ML

PIC32MX110F016D-I/ML

PIC32MX220F032D-I/ML

PIC32MX210F016D-I/ML

PIC32MX120F032D-V/ML

PIC32MX110F016D-V/ML

PIC32MX220F032D-V/ML

PIC32MX210F016D-V/ML

PIC32MX120F032DT-V/ML

PIC32MX110F016DT-V/ML

PIC32MX220F032DT-V/ML

PIC32MX210F016DT-V/ML

MTCH6301T-I/ML

PIC32MX120F032DT-I/ML

PIC32MX110F016DT-I/ML

PIC32MX220F032DT-I/ML

PIC32MX210F016DT-I/ML

PIC32MX120F032D-50I/ML

PIC32MX220F032D-50I/ML

PIC32MX120F032DT-50I/ML

PIC32MX220F032DT-50I/ML

PIC32MX150F128D-I/ML

PIC32MX130F064D-I/ML

PIC32MX250F128D-I/ML

PIC32MX230F064D-I/ML

PIC32MX150F128D-V/ML

PIC32MX130F064D-V/ML

PIC32MX250F128D-V/ML

PIC32MX230F064D-V/ML

PIC32MX150F128DT-V/ML

PIC32MX130F064DT-V/ML

PIC32MX250F128DT-V/ML

PIC32MX230F064DT-V/ML

PIC32MX250F128DT-I/ML026

PIC32MX150F128DT-I/ML

PIC32MX130F064DT-I/ML

PIC32MX250F128DT-I/ML

PIC32MX230F064DT-I/ML

PIC32MX150F128D-50I/ML

PIC32MX250F128D-50I/ML

PIC32MX150F128DT-50I/ML

PIC32MX250F128DT-50I/ML

PIC32MX170F256D-I/ML

PIC32MX270F256D-I/ML

PIC32MX170F256D-V/ML

PIC32MX270F256D-V/ML

PIC32MX170F256DT-V/ML

PIC32MX270F256DT-V/ML

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PIC32MX170F256DT-I/ML

PIC32MX270F256DT-I/ML

PIC32MX170F256D-50I/ML

PIC32MX270F256D-50I/ML

PIC32MX170F256DT-50I/ML

PIC32MX270F256DT-50I/ML

DSPIC33EP512GP502-E/MM

DSPIC33EP512MC202-E/MM

DSPIC33EP512MC502-E/MM

PIC24EP512GP202-E/MM

DSPIC33EP512GP502-I/MM

DSPIC33EP512MC202-I/MM

DSPIC33EP512MC502-I/MM

PIC24EP512GP202-I/MM

PIC24EP512MC202-I/MM

DSPIC33EP512GP502T-H/MM

DSPIC33EP512MC202T-H/MM

DSPIC33EP512MC502T-H/MM

PIC24EP512GP202T-H/MM

PIC24EP512MC202T-H/MM

DSPIC33EP512GP502-H/MM

DSPIC33EP512MC202-H/MM

DSPIC33EP512MC502-H/MM

PIC24EP512GP202-H/MM

PIC24EP512MC202-H/MM

DSPIC33EP512GP502T-I/MM

DSPIC33EP512GP502T-E/MM

DSPIC33EP512MC502T-E/MM

DSPIC33EP64GP502-E/MM

DSPIC33EP64MC202-E/MM

DSPIC33EP64MC502-E/MM

PIC24EP64GP202-E/MM

PIC24EP64MC202-E/MM

DSPIC33EP64GP502-I/MM

DSPIC33EP64MC202-I/MM

DSPIC33EP64MC502-I/MM

PIC24EP64GP202-I/MM

PIC24EP64MC202-I/MM

DSPIC33EP64GP502T-H/MM

DSPIC33EP64MC202T-H/MM

DSPIC33EP64MC502T-H/MM

PIC24EP64GP202T-H/MM

PIC24EP64MC202T-H/MM

DSPIC33EP64GP502-H/MM

DSPIC33EP64MC202-H/MM

DSPIC33EP64MC502-H/MM

PIC24EP64GP202-H/MM

PIC24EP64MC202-H/MM

DSPIC33EP64MC202T-I/MM



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DSPIC33EP64MC502T-I/MM  
PIC24EP64GP202T-I/MM  
PIC24EP64MC202T-I/MM  
DSPIC33EP64GP502T-E/MM  
DSPIC33EP64MC202T-E/MM  
DSPIC33EP64MC502T-E/MM  
PIC24EP64MC202T-E/MM  
DSPIC33EP128MC202-E/MM  
PIC24EP128GP202-E/MM  
PIC24EP128GP202-I/MM038  
DSPIC33EP128GP502-I/MM  
DSPIC33EP128MC202-I/MM  
DSPIC33EP128MC502-I/MM  
PIC24EP128GP202-I/MM  
PIC24EP128GP202T-I/MM038  
DSPIC33EP128GP502T-I/MM  
DSPIC33EP128MC202T-I/MM  
DSPIC33EP128MC502T-I/MM  
DSPIC33EP128MC502T-E/MM  
DSPIC33EP128MC202T-E/MM  
DSPIC33EP256GP502-E/MM  
DSPIC33EP256MC202-E/MM  
DSPIC33EP256MC502-E/MM  
PIC24EP256GP202-E/MM  
PIC24EP256MC202-E/MM  
HA7619-I/MM028  
DSPIC33EP256GP502-I/MM  
DSPIC33EP256MC202-I/MM  
DSPIC33EP256MC502-I/MM  
PIC24EP256GP202-I/MM  
PIC24EP256MC202-I/MM  
DSPIC33EP256GP502T-H/MM  
DSPIC33EP256MC202T-H/MM  
DSPIC33EP256MC502T-H/MM  
PIC24EP256GP202T-H/MM  
PIC24EP256MC202T-H/MM  
DSPIC33EP256GP502-H/MM  
DSPIC33EP256MC202-H/MM  
DSPIC33EP256MC502-H/MM  
PIC24EP256GP202-H/MM  
PIC24EP256MC202-H/MM  
HA7619T-I/MM028  
DSPIC33EP256GP502T-I/MM  
DSPIC33EP256MC202T-I/MM  
DSPIC33EP256MC502T-I/MM  
PIC24EP256GP202T-I/MM  
PIC24EP256MC202T-I/MM  
DSPIC33EP256GP502T-E/MM  
DSPIC33EP256MC202T-E/MM

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DSPIC33EP256MC202T-E/MM

PIC24EP256GP202T-E/MM

PIC24EP256MC202T-E/MM

PIC24EP32MC202-E/MM021

DSPIC33EP32GP502-E/MM

DSPIC33EP32MC202-E/MM

DSPIC33EP32MC502-E/MM

PIC24EP32GP202-E/MM

PIC24EP32MC202-E/MM

DSPIC33EP32GP502-I/MM

DSPIC33EP32MC202-I/MM

DSPIC33EP32MC502-I/MM

PIC24EP32GP202-I/MM

PIC24EP32MC202-I/MM

DSPIC33EP32MC202-H/MM

DSPIC33EP32GP502T-I/MM

DSPIC33EP32MC202T-I/MM

DSPIC33EP32MC502T-I/MM

PIC24EP32GP202T-I/MM

PIC24EP32MC202T-E/MM021

DSPIC33EP32GP502T-E/MM

DSPIC33EP32MC202T-E/MM

DSPIC33EP32MC502T-E/MM

PIC24EP32GP202T-E/MM

DSPIC33EP64GS402-E/MMC02

DSPIC33EP16GS502-E/MMC03

DSPIC33EP64GS502-E/MM

DSPIC33EP32GS502-E/MM

DSPIC33EP16GS502-E/MM

DSPIC33EP32GS402-I/MMC01

DSPIC33EP64GS402-I/MMC02

DSPIC33EP64GS502-I/MMC07

DSPIC33EP64GS502-I/MMC12

DSPIC33EP32GS402-I/MM

DSPIC33EP64GS502-I/MM

DSPIC33EP32GS502-I/MM

DSPIC33EP16GS502-I/MM

DSPIC33EP32GS402T-I/MMC01

DSPIC33EP64GS402T-I/MMC02

DSPIC33EP64GS502T-I/MMC07

DSPIC33EP64GS502T-I/MMC12

DSPIC33EP32GS402T-I/MM

DSPIC33EP64GS502T-I/MM

DSPIC33EP32GS502T-I/MM

DSPIC33EP16GS502T-I/MM

DSPIC33EP64GS402T-E/MMC02

DSPIC33EP64GS502T-E/MM

DSPIC33EP32GS502T-E/MM

DSPIC33EP16GS502T-E/MM

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DSPIC33EV128GM002-E/MM  
DSPIC33EV128GM102-E/MM  
DSPIC33EV64GM002-E/MM  
DSPIC33EV64GM102-E/MM  
DSPIC33EV32GM002-E/MM  
DSPIC33EV32GM102-E/MM  
DSPIC33EV128GM002-I/MM  
DSPIC33EV128GM102-I/MM  
DSPIC33EV64GM002-I/MM  
DSPIC33EV64GM102-I/MM  
DSPIC33EV32GM002-I/MM  
DSPIC33EV32GM102-I/MM  
DSPIC33EV128GM002-H/MM  
DSPIC33EV128GM102-H/MM  
DSPIC33EV64GM002-H/MM  
DSPIC33EV64GM102-H/MM  
DSPIC33EV32GM002-H/MM  
DSPIC33EV32GM102-H/MM  
DSPIC33EV128GM002T-I/MM  
DSPIC33EV128GM102T-I/MM  
DSPIC33EV64GM002T-I/MM  
DSPIC33EV64GM102T-I/MM  
DSPIC33EV32GM002T-I/MM  
DSPIC33EV32GM102T-I/MM  
DSPIC33EV256GM002-E/MM  
DSPIC33EV256GM102-E/MM  
DSPIC33EV256GM002-I/MM  
DSPIC33EV256GM102-I/MM  
DSPIC33EV256GM002-H/MM  
DSPIC33EV256GM102-H/MM  
DSPIC33EV256GM002T-I/MM  
DSPIC33EV256GM102T-I/MM  
PIC24FJ64GB202-E/MM  
PIC24FJ128GB202-I/MM  
PIC24FJ64GB202-I/MM  
PIC24FJ128GB202T-I/MM  
PIC24FJ64GB202T-I/MM  
PIC24FJ128GA202-E/MM  
PIC24FJ64GA202-E/MM  
PIC24FJ128GA202-I/MM  
PIC24FJ64GA202-I/MM  
PIC24FJ128GA202T-I/MM  
PIC24FJ64GA202T-I/MM  
PIC32MX174F256B-I/MM  
PIC32MX274F256B-I/MM  
PIC32MX154F128B-I/MM  
PIC32MX254F128B-I/MM  
PIC32MX174F256B-V/MM  
PIC32MX274F256B-V/MM

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PIC32MX154F128B-V/MM  
PIC32MX254F128B-V/MM  
PIC32MX174F256BT-V/MM  
PIC32MX274F256BT-V/MM  
PIC32MX154F128BT-V/MM  
PIC32MX254F128BT-V/MM  
PIC32MX174F256BT-I/MM  
PIC32MX274F256BT-I/MM  
PIC32MX154F128BT-I/MM  
PIC32MX254F128BT-I/MM  
PIC32MX120F032B-I/ML  
PIC32MX110F016B-I/ML  
PIC32MX220F032B-I/ML  
PIC32MX210F016B-I/ML  
PIC32MX120F032B-V/ML  
PIC32MX110F016B-V/ML  
PIC32MX220F032B-V/ML  
PIC32MX210F016B-V/ML  
PIC32MX120F032BT-V/ML  
PIC32MX110F016BT-V/ML  
PIC32MX220F032BT-V/ML  
PIC32MX210F016BT-V/ML  
PIC32MX120F032BT-I/ML  
PIC32MX110F016BT-I/ML  
PIC32MX220F032BT-I/ML  
PIC32MX210F016BT-I/ML  
PIC32MX120F032B-50I/ML  
PIC32MX220F032B-50I/ML  
PIC32MX120F032BT-50I/ML  
PIC32MX220F032BT-50I/ML  
SSC7150-ML-AB0  
SSC7150-ML-AB1  
PIC32MX150F128B-I/ML  
PIC32MX130F064B-I/ML  
PIC32MX250F128B-I/ML  
PIC32MX230F064B-I/ML  
PIC32MX150F128B-V/ML  
PIC32MX130F064B-V/ML  
PIC32MX250F128B-V/ML  
PIC32MX230F064B-V/ML  
PIC32MX150F128BT-V/ML  
PIC32MX130F064BT-V/ML  
PIC32MX250F128BT-V/ML  
PIC32MX230F064BT-V/ML  
SSC7150-ML-AB0-TR  
SSC7150-ML-AB1-TR  
PIC32MX250F128BT-I/ML028  
PIC32MX150F128BT-I/ML  
PIC32MX130F064BT-I/ML

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PIC32MX250F128BT-I/ML

PIC32MX230F064BT-I/ML

PIC32MX150F128B-50I/ML

PIC32MX250F128B-50I/ML

PIC32MX150F128BT-50I/ML

PIC32MX250F128BT-50I/ML